

Product Change Notification

Change Notification #: 116871 - 00

Change Title: Select Intel® CoreTM & Intel® Celeron®

Processors, PCN 116871-00, Manufacturing Site, Adding Manufacturing Site in Malaysia for Partial and/or Full Flow Manufacturing

Date of Publication: June 4, 2019

Key Characteristics of the Change:

Manufacturing Site

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: July 12, 2019
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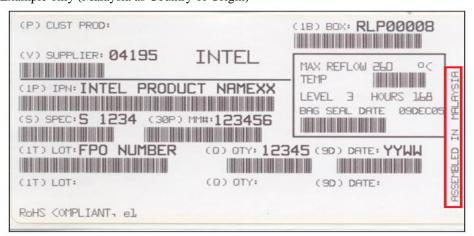
Description of Change to the Customer:

Intel will be qualifying an existing certified Manufacturing Site in Malaysia to perform full flow manufacturing (Assembly, Test, and Finish) as well as partial manufacturing on the products listed in the Products Affected / Intel Ordering Codes table below. Products would then be manufactured among the two qualified sites, China and Malaysia.

Both the Malaysia Manufacturing Site and the China Manufacturing Sites will be certified equivalent (form, fit, function, and reliability) for the affected products and technologies of this change.

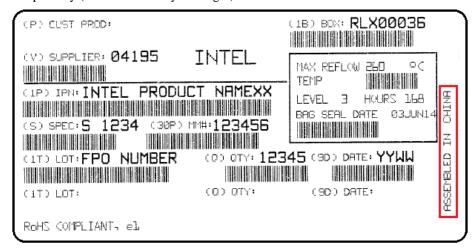
With the possibility of full flow, or partial flow of material now coming from Malaysia, the value for the Country of Origin, on box labels, will now show either site (depending on the site which performed Assembly).

Example only (Malaysia as Country of Origin)



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Example only (China as Country of Origin)



Customer Impact of Change and Recommended Action:

Customers can expect to see this change as early as early mid July 2019. Customers should notify their receiving department of the additional country involved in the manufacturing of the products impacted.

It is possible that Customers may receive finished materials manufactured entirely at one of the two qualified sites or material split between the two sites to accomplish Assembly, Test and Finish.

Customers may contact their Intel Field Sales Representative or the contacts listed on the last page of this Product Change Notification appropriate to your geo with questions.

Products Affected / Intel Ordering Codes:

Marketing Name	Platform	Product Code	S-Spec	MM#
Intel® Core™ i7-2710QE Processor	MOBILE	FF8062700841002	S R02T	910243
Intel® Core™ i5-2510E Processor	MOBILE	FF8062700853304	S R02U	910244
Intel® Core™ i3-2330E Processor	MOBILE	FF8062700849000	S R02V	910245
Intel® Core™ i7-2715QE Processor	MOBILE	AV8062700843908	S R076	911594
Intel® Core™ i3-2310E Processor	MOBILE	AV8062700849116	S R077	911597
Intel® Core™ i7-2655LE Processor	MOBILE	AV8062700849508	S R078	911598
Intel® Core™ i7-2610UE Processor	MOBILE	AV8062700849607	S R079	911599
Intel® Core™ i5-2515E Processor	MOBILE	AV8062700853208	S R075	911601
Intel® Core™ i7-3615QE Processor	EMBEDDED	AV8063801117503	S R0NC	919818
Intel® Core™ i7-3612QE Processor	EMBEDDED	AV8063801149203	S R0ND	919819
Intel® Core™ i7-3610QE Processor	EMBEDDED	AW8063801118306	S R0NP	919875
Intel® Core™ i5-3610ME Processor	EMBEDDED	AW8063801115901	S R0QJ	920312
Intel® Core™ i5-3610ME Processor	EMBEDDED	AV8063801116102	S R0QK	920313
Intel® Core™ i7-3555LE Processor	EMBEDDED	AV8063801116903	S R0T5	921365
Intel® Core™ i7-3517UE Processor	EMBEDDED	AV8063801149402	S R0T6	921368
Intel® Core TM i3-3120ME Processor	EMBEDDED	AV8063801117301	S R0WL	923000
Intel® Core™ i3-3120ME Processor	EMBEDDED	AW8063801117902	S R0WM	923001
Intel® Core™ i3-3217UE Processor	EMBEDDED	AV8063801149502	S ROWN	923002
Intel® Core™ i7-4700EQ Processor	EMBEDDED	CL8064701483802	S R17L	929205
Intel® Core™ i5-4400E Processor	EMBEDDED	CL8064701483902	S R17M	929206
Intel® Core™ i3-4100E Processor	EMBEDDED	CL8064701484002	S R17N	929207

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Marketing Name	Platform	Product Code	S-Spec	MM#
Intel® Celeron® Processor 2002E	EMBEDDED	CL8064701484102	S R17P	929208
Intel® Core™ i5-4402E Processor	EMBEDDED	CL8064701528501	S R17Q	929209
Intel® Core™ i3-4102E Processor	EMBEDDED	CL8064701528601	S R17R	929210
Intel® Celeron® Processor 2000E	EMBEDDED	CL8064701528700	S R17S	929211
Intel® Core™ i7-4701EQ Processor	EMBEDDED	CL8064701575100	S R1H1	930700
Intel® Core™ i3-4112E Processor	EMBEDDED	CL8064701588505	S R1T0	932845
Intel® Core™ i5-4422E Processor	EMBEDDED	CL8064701588605	S R1T1	932847
Intel® Core™ i3-4110E Processor	EMBEDDED	CL8064701589005	S R1T2	932849
Intel® Core™ i5-4410E Processor	EMBEDDED	CL8064701589205	S R1T4	932853
Intel® Core™ i7-4700EC Processor	EMBEDDED	CL8064701830000	S R1VZ	934873
Intel® Core TM i7-4702EC Processor	EMBEDDED	CL8064701830100	S R1W0	934875

PCN Revision History:

Date of Revision: Revision Number: Reason:

June 4, 2019 Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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